


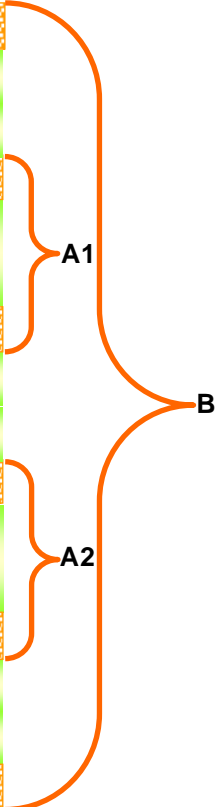












**Schematic Key for Multilayer and HDI-Technology Build-Ups**

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

**06 160 FR4 70 L36.35 P10**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**06\_160\_FR4\_70\_L36.35\_p10**

| Layers          | in $\mu$  | Material | Build-Up   | Assembly   |
|-----------------|-----------|----------|--|--|
| <b>Layer-1</b>  | 70 $\mu$  | Copper   |    |  |
|                 | 100 $\mu$ | Prepreg  | (100 $\mu$ PrePreg-Type: 2125)   |  |
|                 | 100 $\mu$ | Prepreg  |    |  |
| <b>Layer-2</b>  | 35 $\mu$  | Copper   |    |  |
|                 | 360 $\mu$ | L-FR4    |    |  |
| <b>Layer-3</b>  | 35 $\mu$  | Copper   |   |  |
|                 | 100 $\mu$ | Prepreg  |  |  |
|                 | 100 $\mu$ | Prepreg  |  |  |
| <b>Layer-4</b>  | 35 $\mu$  | Copper   |  |  |
|                 | 360 $\mu$ | L-FR4    |  |  |
| <b>Layer-5</b>  | 35 $\mu$  | Copper   |  |  |
|                 | 100 $\mu$ | Prepreg  |  |  |
|                 | 100 $\mu$ | Prepreg  |  |  |
| <b>Layer-99</b> | 70 $\mu$  | Copper   |  |  |

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